



FEATURES

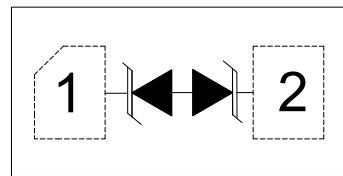
- ✧ Solid-state silicon technology
- ✧ Low clamping voltage and low leakage current
- ✧ Working voltage:7V
- ✧ Ultra-low capacitance
- ✧ RoHS compliant



MAIN APPLICATIONS

- ✧ Cellular handsets
- ✧ USB V_{BUS} and CC line protection
- ✧ Microphone line protection
- ✧ GPIO protection

DFN1006-2L(Bottom view)



Pin Configuration(Top view)

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- ✧ IEC61000-4-4 (EFT)40A(5/50ns)
- ✧ IEC61000-4-5 (Lightning) 6A (8/20μs)

MECHANICAL CHARACTERISTICS

- ✧ DFN1006-2L package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Marking code: 7A
- ✧ Quantity per reel:10,000pcs
- ✧ Lead finish: lead free

ABSOLUTE MAXIMUM RATINGS($T_A=25^\circ\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	84	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS($T_A=25^\circ C$)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				7	V
Reverse breakdown voltage	V_{BR}	$I_T=1mA$	7.2		10.5	V
Reverse holding voltage	V_H	$I_H=50mA$	7.2		10.5	V
Reverse leakage current	I_R	$V_{RWM}=7V$			0.1	μA
Peak pulse current	I_{PP}	$t_P=8/20\mu s$			6	A
Clamping voltage	$V_C^{①}$	$I_{PP}=16A, t_P=100ns$		12		V
Dynamic resistance	$R_{DYN}^{①}$			0.28		Ω
Clamping voltage	$V_C^{②}$	$V_{ESD}=8kV$		12		V
Clamping voltage	$V_C^{③}$	$I_{PP}=1A, t_P=8/20\mu s$		9	11	V
		$I_{PP}=6A, t_P=8/20\mu s$		12	14	V
Junction capacitance	C_J	$V_{RWM}=0V, f=1MHz$		10	13	pF
		$V_{RWM}=2.5V, f=1MHz$		8	11	pF

① TLP parameter: $Z_0=50\Omega, t_P=100ns, tr=2ns$, averaging window from 60ns to 80ns. R_{DYN} is calculated from 4A to 16A.

② Contact discharge mode, according to IEC61000-4-2.

③ Non-repetitive current pulse, according to IEC61000-4-5.

RATINGS AND V-I CHARACTERISTICS CURVES ($T_A=25^\circ\text{C}$, unless otherwise noted)

**FIG.1:V- I curve characteristics
(Bi-directional)**

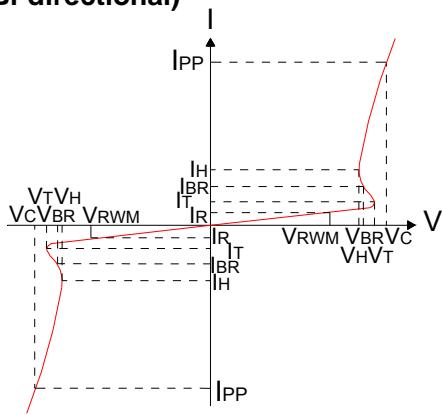


FIG.3: Pulse derating curve

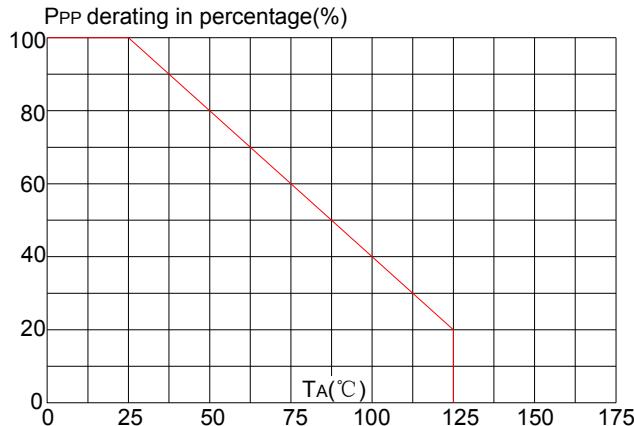


FIG.5: Clamping voltage vs.peak pulse current

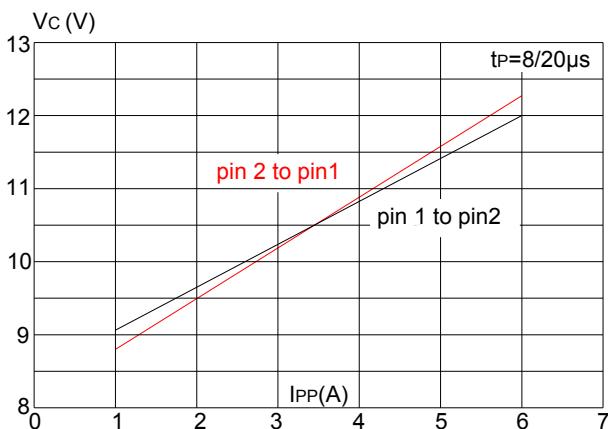


FIG.2: Pulse waveform (8/20μs)

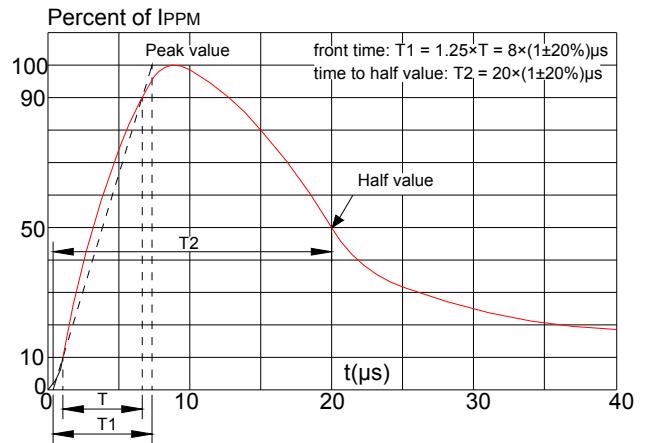


FIG.4: ESD clamping (30kV contact)

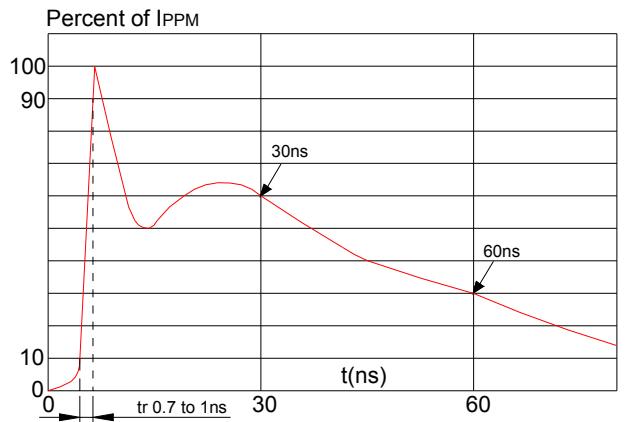
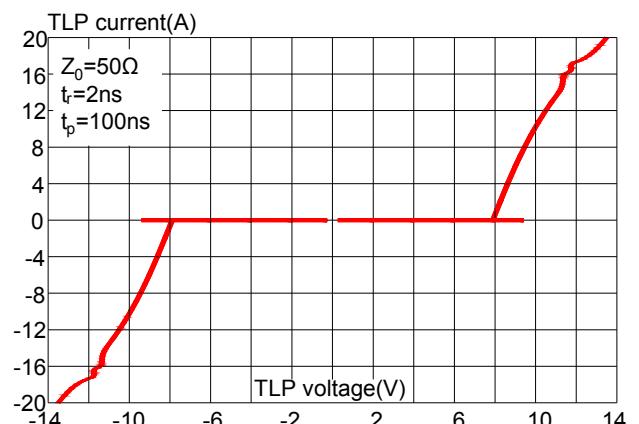
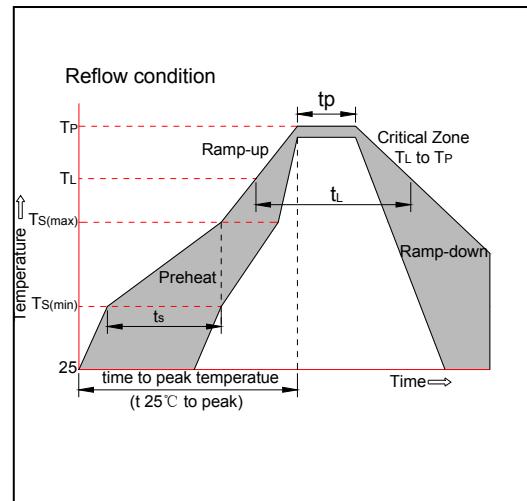


FIG.6: TLP Measurement

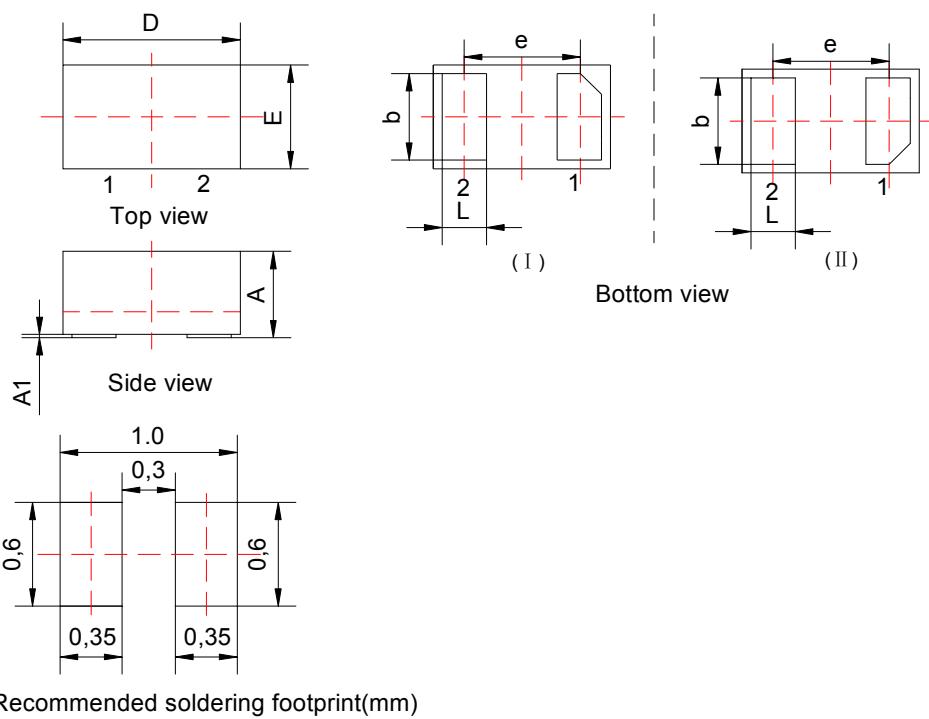


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(\min)}$)	+150°C
	-Temperature Max($T_{s(\max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3°C/sec. Max
$T_{s(\max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

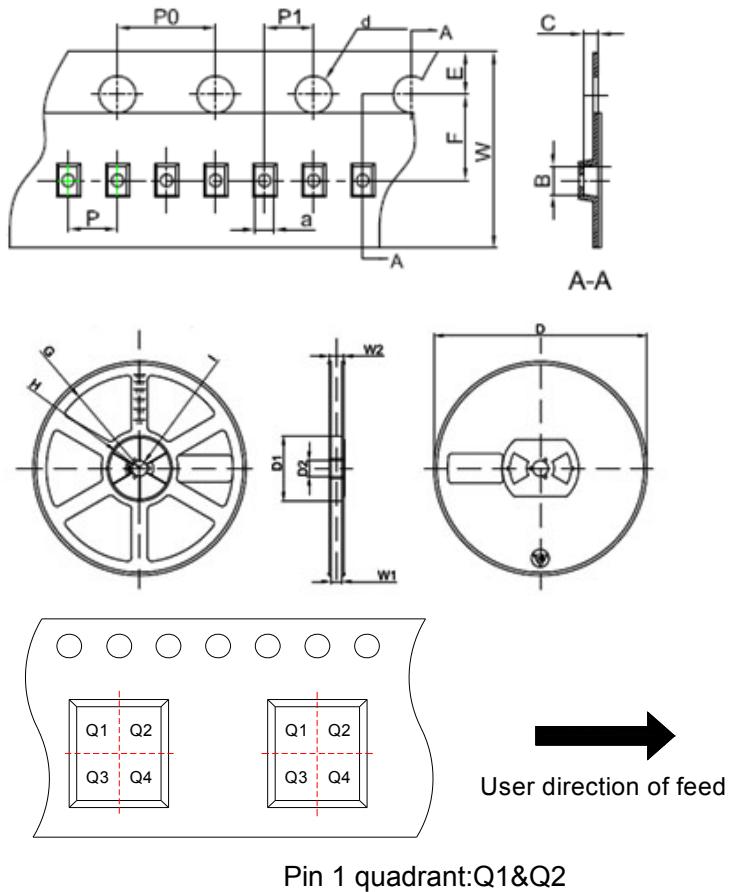


PACKAGE MECHANICAL DATA



Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.50	0.55	0.016	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65BSC			0.026BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
L	0.20	0.25	0.30	0.008	0.010	0.012

TAPE AND REEL INFORMATION-DFN1006-2L



Symbol	Millimeters	Inches
	Typ.	Typ.
a	0.66	0.026
B	1.15	0.045
C	0.66	0.026
d	Φ1.50	Φ0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	2.00	0.079
P1	2.00	0.079
W	8.00	0.315
D	Φ178	Φ7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.00	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCIPTION
JEB07DFA	DFN1006-2L	10,000	7 inch reel pack

MARKING CODE

Part Number	Marking Code
JEB07DFA	

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